

TRANSMITTAL  
FORM

Application Serial Number---	09/932,754
Filing Date	August 17, 2001
First Named Inventor	Kamieniecki
Group Art Unit	2829
Examiner Name	Hollington
Attorney Docket No.	QCS-001DV3
Patent No.	Not applicable
Issue Date	Not applicable

## ENCLOSURES (check all that apply)

<input type="checkbox"/> Fee Transmittal Form <input type="checkbox"/> Check Attached <input type="checkbox"/> Copy of Fee Transmittal Form <input checked="" type="checkbox"/> Amendment/Response <input type="checkbox"/> Preliminary <input type="checkbox"/> After Final <input type="checkbox"/> Affidavits/declaration(s) <input type="checkbox"/> Letter to Official Draftsperson including Drawings [Total Sheets ____] <input type="checkbox"/> Petition for Extension of Time <input type="checkbox"/> Information Disclosure Statement <input type="checkbox"/> Form PTO-1449 <input type="checkbox"/> Copies of IDS Citations <input type="checkbox"/> Certified Copy of Priority Document(s) <input type="checkbox"/> Sequence Listing submission <input type="checkbox"/> Paper Copy/CD <input type="checkbox"/> Computer Readable Copy <input type="checkbox"/> Statement verifying identity of above	<input type="checkbox"/> Copy of Notice to File Missing Parts of Application (PTO-1553) <input type="checkbox"/> Formal Drawing(s) <input type="checkbox"/> Request For Continued Examination (RCE) Transmittal <input type="checkbox"/> Power of Attorney (Revocation of Prior Powers) <input type="checkbox"/> Terminal Disclaimer <input type="checkbox"/> Executed Declaration and Power of Attorney for Utility or Design Patent Application <input type="checkbox"/> Small Entity Statement <input type="checkbox"/> CD(s) for large table or computer program <input type="checkbox"/> Amendment After Allowance <input type="checkbox"/> Request for Certificate of Correction <input type="checkbox"/> Certificate of Correction (in duplicate)	<input type="checkbox"/> Notice of Appeal to Board of Patent Appeals and Interferences <input type="checkbox"/> Appeal Brief (in triplicate) <input type="checkbox"/> Status Inquiry <input checked="" type="checkbox"/> Return Receipt Postcard <input checked="" type="checkbox"/> Certificate of First Class Mailing under 37 C.F.R. 1.8 <input type="checkbox"/> Certificate of Facsimile Transmission under 37 C.F.R. 1.8 <input type="checkbox"/> Additional Enclosure(s) (please identify below)
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PATENT

Atty. Docket No. OCS-001DV3 (6695/2)

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANTS: Kamieniecki et al.

SERIAL NUMBER: 09/932,754

ART UNIT: 2829

FILING DATE: August 17, 2001

EXAMINER: J. Hollington

TITLE: Real-Time In-Line Testing Of Semiconductor Wafers

Assistant Commissioner for Patents  
Washington, D.C. 20231

AMENDMENT and RESPONSE

Sir:

In response to the Office Action mailed on May 9, 2002, in connection with the patent application identified above, for which the period of response ends on August 9, 2002, Applicants respectfully request entry of this amendment and response, reconsideration, and passage of this application to allowance. In the event that any additional fees are due, the Commissioner is hereby authorized to charge any such fees to Attorney's Deposit Account No. 20-0531.

Please amend the application, without prejudice, as follows:

In the Claims:

Please amend the following claim:

53. (Twice Amended) A semiconductor wafer fabrication system comprising:

a sealed chamber for processing said semiconductor wafer having a first surface and a second surface; and a head assembly comprising:

a modulated light source exposing at least a portion of said semiconductor wafer to light having a wavelength and modulated at a frequency; and

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